

## Data sheet Product ICK BGA 19 x 19 x 6

Heatsinks and active heatsinks for processors>Heatsinks for BGAs  
19 x 19 x 6 mm, for IC design BGA and others

### Features

way of fixation:	<ul style="list-style-type: none"> <li>• therm. conductive foil</li> <li>• therm. cond. adhesive</li> </ul>
socket:	universal
suitable for processor type:	universal
width:	19 mm
height:	6 mm
plate thickness:	1.8 mm
length:	19 mm
thermal resistance:	27 - 11 K/W
dissipation loss:	2 W
surface:	black anodised

### Technical Drawing

